Effect of Nano-additive on the Bonding Strength and Formaldehyde Emission of the Plywood Adhesive during Manufacturing of Wood Based Panel Products

S.C.Sahoo, Amitava Sil, Dharm Pal

Abstract: Nano science and nano technology provides numerous opportunities for enhancing the properties of wood based panel products. In this study an extender was made using nano silicon dioxide (Sio2), nano calcium carbonate(CaCo3) with some specialty chemicals at a certain reciprocal proportion. Efficacy study was carried out with both phenolic and amino resin in terms of rheological and formaldehyde emission test using reinforcement of nano additive as extender at different concentration level. The plywood panels has been tested as per IS: 1734-1983 for mechanical properties. The rheological and adhesive properties has been tested as per IS 848: 2006. The test data reveals that enhancement of rheological, bonding and mechanical properties have been achieved after reinforcement of synthetic resin. The increase in the percentage of nano-additive caused an increase of viscosity, glue shear strength and minimizing the formaldehyde emission than using individual nano silicon dioxide (Sio2), nano calcium carbonate(CaCO3) instead of the extender made by combination of above. Using nano additive extender at 5%, there is an increase in glue shear strength in the glue line and enhanced rheological properties in amino resin based adhesive was observed.

Keywords: Composite wood products, nanotechnology, nano additives, nano material-reinforced adhesives.

I. INTRODUCTION

 ${f A}$ dditives are basically made with special chemicals when added in small concentration, it enhances the adhesive properties and reduces the cost of the glue used in wood based panel industries to manufacture wood composites. Additives are inexpensive and therefore used to reduce the high cost of these synthetic resins. The focus is on green technology, sustain-ability, lower cost and safe products have led to the introduction of newer additives and chemistries. At the same time, it has been proven that nano-SiO₂ does not significantly affect the curing time of the resin and there is not necessary to change the press conditions (Lin et al. 2006). Addition of nano- SiO₂ does not have an effect in the thermal stability of the resin (Roumeli et al. 2012). Considering this, the research was undertaken on the possibility of improving the properties of boards made of rape straw of nano-SiO2 to the Urea Formaldehyde resin. It was revealed in earlier numerous

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studies, that rape straw may constitute valuable substitute for wood chips in particle boards manufacturing on condition that relevant type or quantity of binder is applied (Dukarska et al. 2006, Keyhole et al. 2005, Paubicki et al. 2003. Some researchers have reported the good performance of nano clays when used as a reinforcing element in wood adhesives, obtaining significant gains in resistance, besides increasing the thermal stability (Moya et al. 2015). Wood Adhesives are classified into two types (i) natural viz . starch, dextrin, protein glue, vegetable & animal glues (ii) Synthetic viz. thermosetting and thermoplastic resin. Due to high cost of these adhesives, certain materials are often added to reduce the cost of adhesive and to impart special effects on the mixture. These materials are called additive and are classified as fortifier, extender and fillers. These materials are inexpensive and therefore used to cut down the high cost of the synthetic resin. Depending on the nature of the resin, additive and wood species, the additive normally make up about 14% of the total cost of the adhesive mixture.

II. EXPERIMENTAL METHOD

Commercial grade formalin, caustic, urea etc. used for resin synthesis. Wood veneers used for manufacture of plywood were mainly Dipterocarpus spp. (Gurjan). The nano SiO_2 and nano $CaCO_3$ were procured from local market having properties (moisture content as to 9%, density as 2.4 g/cm3 to 2.93 g/cm3). respectively and dry particle size of (15 -40) nm Author (s) can send paper in the given email address of the journal. There are two email address. It is compulsory to send paper in both email address.

A. Urea Formaldehyde Resin

The urea formaldehyde plywood resin was manufactured as per the process given (Sahoo et al 2014) and taken for the study of extender quality. Properties of the resin has been studied.

B. Extender formulation

An extender was formulated by taking starch based material as a major percentage with some filler and nano particles like SiO_2 and $CaCO_3$ at certain proportion. The extender concentrations from (1-6) % on the basis of the weight of liquid resin was taken along with only urea formaldehyde resin as control to assess the quality of the

extender as well as the ply board manufactured.

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C. Glue formulation

Urea formaldehyde based glue was prepared by using extender starting from concentration 1.0% to 6% along with only urea formaldehyde resin without extender as a control. The glue was prepared by using laboratory stirrer for 30 - 45minutes. The viscosity in terms of flow time was measured in B₆ cup (IS:3944-1982). Ref. Tab IV.

D. Properties of Extender

The different properties of the extender like ash content, PH, particle size etc was carried out as per IS:1508.

E. Plywood Manufacturing

600 x 600 x 12mm ply board was manufactured by taking veneer of moisture content around 5 to 7% and glue applied at the rate of (280- 320) gm/m^2 on double glue line basis. The specific pressure was applied for 13 minutes at a temperature 115° C. (Ref Tab III)

F. Assessment of adhesive bond

The bond quality of the plyboard was tested for water resistance test as per IS 848:2006 for MR grade. The other parameters relevant to bond quality were tested as per IS:1734-1983 for assessment of bond quality (Ref Tab III and Tab VII).

G. Formaldehyde emission assessment (Perforator value)

Formaldehyde emission value of the ply board made by using extender at various extension level with both UF and PF resin was determined by perforator method as per ENV-717.

III. RESULTS AND DISCUSSION

From the tests of particle size of the extender, it reveals that the particle size of the extender shows satisfactory results and meets as per the requirement of IS 1508 when tested as per sieve designation of 80 micron. The extender when mixed with urea formaldehyde resin shows a homogeneous mixture after mixing of 30 -45 minutes without showing any reaction or adverse effect with resin. The study of the extender shows that, the concentration level i.e. 3 percentage concentration of liquid resin in UF shows satisfactory concentration for glue spreader and adhesive mix viscosity after mixing properly in a glue spreader minimum 30 minutes. The viscosity of adhesive increased using higher percentage of extender made by additive from nano SiO₂ and CaCO₃.

From viscosity study (Ref Tab III), data shows that viscosity of the glue measured in terms of flow time in B₆ (IS : 3944-1982) showed satisfactory results at concentration 3%. Solid content of adhesive mix increases significantly as the concentration of the extender increases. From physico-mechanical property study of plywood, data shows there was a significant change in mechanical i.e at a higher side was achieved of plywood samples made by using extender during pilot scale study.

From the study for manufacture of plywood to assess the rheological properties of extender, the parameters for hot pressing and cold pressing (Ref Tab III), it shows satisfactory rheological properties of the resin and good bonding strength of the plywood. It also shows that the emission value (perforator value) of the plywood after at 3% concentration level was 12.6 mg/100gm compared to blank results 29.2 mg/100 gm of the board wherein it minimizes more than 50% in comparison to blank.

IV. CONCLUSION

The use of nano materials as extender leads to a change in mechanical properties for wood panels even with the addition of a relative lower percentage. Thus the results of this study are acceptable considering the lower quantity of nano SiO₂ and CaCO₃ mix to be an alternative to improve the bond quality of wood based panel. There is a significant reduction of formaldehyde emission by using the nano SiO₂ and CaCO3 based extender. The addition of up to 3% extender resulted in a relative improvement of glue shear strength. On addition of excess nano additive based extender leads to increase the viscosity of the adhesive system which give adverse effect on the bonding quality of the wood based panel. It can be concluded that there was a significant reduction in non volatile content with the addition of nano based extender. It has also shown that nano SiO2 and CaCO3 mixed additive are promising for the improvement of amino base adhesive performance.

Table- I: Properties of resin

| Gel Time at 100°C (seconds) | Flow Time (B4 cup) (seconds) | Solid content (%) | Water tolerance | pH | PH of Cured film | Free formaldehyde (%) |
|--------------------------------------|---------------------------------------|-------------------------|--------------------|-----|------------------------|-----------------------------|
| 73 | 20 | 50.1 | 1:4 | 7.8 | 2.91 | 0.91 |

Table -II: Adhesive mix with different concentration

| | Parts by weight (Pbw) | | | | | | | | | |
|--------------------|----------------------------|-----|-------|----------------|-------|----------------|----------------|--|--|--|
| Component | Level of concentration (%) | | | | | | | | | |
| | C_0 | C1 | C_2 | C ₃ | C_4 | C ₅ | C ₆ | | | |
| UF Resin | 200 | 200 | 200 | 200 | 200 | 200 | 200 | | | |
| Liquid 49% | | | | | | | | | | |
| solid | | | | | | | | | | |
| Extender | 0 | 2.0 | 4.0 | 6.0 | 8.0 | 10.0 | 12.0 | | | |
| NH ₄ Cl | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | 1.0 | | | |
| Liquid NH4 | 1.6 | 1.6 | 1.6 | 1.6 | 1.6 | 1.6 | 1.6 | | | |

Table -III: Board Pressing conditions

| Parameters | Cold Pressing for UF Resin |
|-------------|----------------------------|
| Pressure | 10.5 kg/cm* |
| Temperature | 110°C |
| Time | 12 minutes |



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| Properties | Level of concentration (%) | | | | | | | |
|-------------------|----------------------------|-------|-------|-------|-------|-------|----------------|--|
| | C ₀ | C1 | C2 | C3 | C_4 | C5 | C ₆ | |
| Flow time | 21/B ₄ | 10 | 11.5 | 14 | 16 | 17.5 | 19 | |
| Solid content (%) | 49.6 | 50.2 | 51.1 | 51.8 | 52.7 | 53.9 | 54.8 | |
| Adhesive pH | 6-6.5 | 6-6.5 | 6-6.5 | 6-6.5 | 6-6.5 | 6-6.5 | 6-6.5 | |
| Pot life (hrs) | > 6 | > 6 | > 6 | > 6 | > 6 | > 6 | > 6 | |

Table -IV: Properties of adhesive mix

Table -V: Effect of coverage on Glue Shear Strength with respect to coverage spread = 350± 10 gms/m2 DGL

| | | | Average Glue Shear Strength | | | | | | | | | |
|-------------------------------------|----------------|--|-----------------------------|---------------------|----------|----------------------|--------------------------------|---------------------|--|--|--|--|
| Type of Extender base on nano | Conc Level | Coverage / m ² DGL/kg Liquid UF | | State | | st as per MR rade | Resistance to Mico-organism | | | | | |
| additive | | resin | Load (N) | Wood Failure (%) | Load (N) | Wood Failure (%) | Load (N) | Wood Failure (%) | | | | |
| | C ₀ | 5.68 | 788 | 65 | 720 | 55 | 652 | 50 | | | | |
| | C1 | 5.82 | 799 | 65 | 732 | 55 | 666 | 50 | | | | |
| | C_2 | 5.90 | 808 | 65 | 748 | 55 | 698 | 50 | | | | |
| UF Resin | C3 | 5.96 | 825 | 70 | 762 | 60 | 709 | 55 | | | | |
| | C_4 | 5.98 | 887 | 70 | 775 | 60 | 716 | 55 | | | | |
| | C5 | 5.96 | 896 | 70 | 782 | 60 | 722 | 60 | | | | |
| | C ₆ | 5.98 | 1898 | 70 | 798 | 60 | 738 | 60 | | | | |

Table - VI: Composition of the adhesive mix used to prepare 7 ply of 1.2 mm thickness

| Adhesiv | e mix | Board parameters for | or 7 ply plywood |
|----------------------------|-------|---------------------------|-----------------------|
| Component Parts by weigh | | Characters | Board Parameters (mm) |
| Resin UF Liquid | 200 | Number of plies | 7 |
| NH ₄ Cl 1.0 | | Face longitudinal | 1.0 |
| Liquid NH ₄ 1.6 | | Cross band | 2.2 |
| Extender 3.0 | | Panel core | 2.2 |
| Insecticide(GLP) | 0.5 | Cross band | 2.2 |
| | | Panel core | 2.2 |
| | | Cross band | 2.2 |
| | | Back (Longitudinal grain) | 1.0 |

Table -VII: Physico-Mechanical properties of the plywood

| | Type of Extender | Average Glue Shear Strength | | | | | | Static Bending | | | | Tensile | |
|---|----------------------|-----------------------------|------------------------|-------------|---------------------|------------------------------------|------------------------|--------------------------|--------|--------------------------|--------|----------------------------------|--------|
| | | Dry State | | Wet State | | Resistance to Mico-organis m | | MoR (N/mm ²) | | MoE (N/mm ²) | | Strength (N/mm ²) | |
| | used (%) | Load (N) | Wood Failure (%) | Load (N) | Wood Failure (%) | Load (N) | Wood Failure (%) | Along | Across | Along | Across | Along | Across |
| 1 | UF+Conv. Extender | 776 | 70 | 722 | 60 | 696 | 55 | 38.26 | 39.64 | 3285 | 2842 | 26.52 | 29.53 |
| 2 | UF+Nano. Extender | 825 | 75 | 764 | 65 | 718 | 60 | 46.22 | 50.26 | 4655 | 4687 | 34.85 | 32.84 |

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REFERENCES

- 1. LinQ., Yang G., Liu J., Roa J. 2006: China 2, PP- 230-237.
- Roumeli E., Papadopoulou E. Pavlidou E., Vourlias G., Bikiaris D., Paraskevopoulos K.M., Chrissafis K. *Thermochimica Acta*, 2012, 527, 33-39.
- Dukarska D., *Cka J. 2009: Ann. WULS-SGGW, Wood Technol, 68, 198-202.
- Li, Z., J. Wang, C. Li, Z. Gu, L. Cheng and Y. Hong, 2015 Carbohydrate Polymers, 2015, 115, 394-400
- Zhou, X., A. Pizzi And G. Du, Journal of Adhesion Science and Technology, 2012, 26(10-11), 1341-1348.
- 6. Bureau of Indian Standards IS 1508 1972,

7. Bureau of Indian Standards IS 3944 – 1982, Bureau of Indian Standards IS 848 – 1992,

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